

DO NOT SCALE FROM THIS PRINT

DESIGNED & DIMENSIONED IN MILLIMETERS [INCHES]

PCIE-LP-XX-01-X-DV-A-XX-X-XX

No OF LANES
-01, -04, -08, -16

CARD THICKNESS
-01: 1.57mm (.062) CARD

PLATING SPECIFICATION
-F: 3µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL
-S: 30µ" SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL
-L: 10µ" LIGHT SELECTIVE GOLD IN CONTACT AREA, MATTE TIN ON TAIL

PACKAGING
BLANK: TRAY (FOR 16 LANES ONLY)
-TR: TAPE & REEL (SEE NOTES 7 & 8)
-FR: FULL REEL QTY TAPE & REEL (SEE NOTES 7 & 8)
(-XR PACKAGING AVAILABLE FOR -01, -04 & -08 LANES ONLY)

PICK & PLACE OPTION
-K: POLYIMIDE FILM PAD (SEE FIG 3, SHT 2)

OPTION
-WT: WELD TAB (SEE FIG 2, SHT 2)

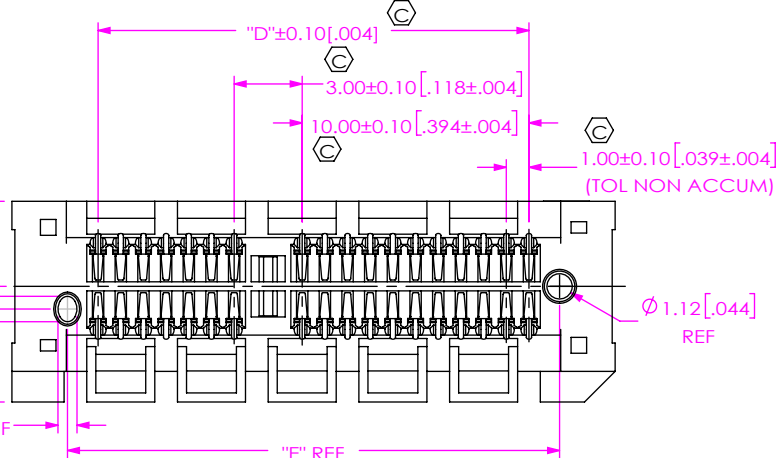
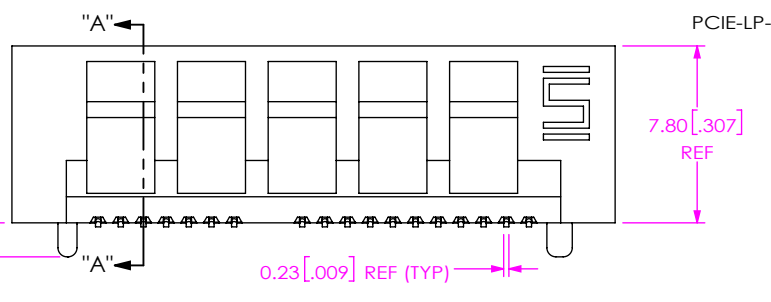
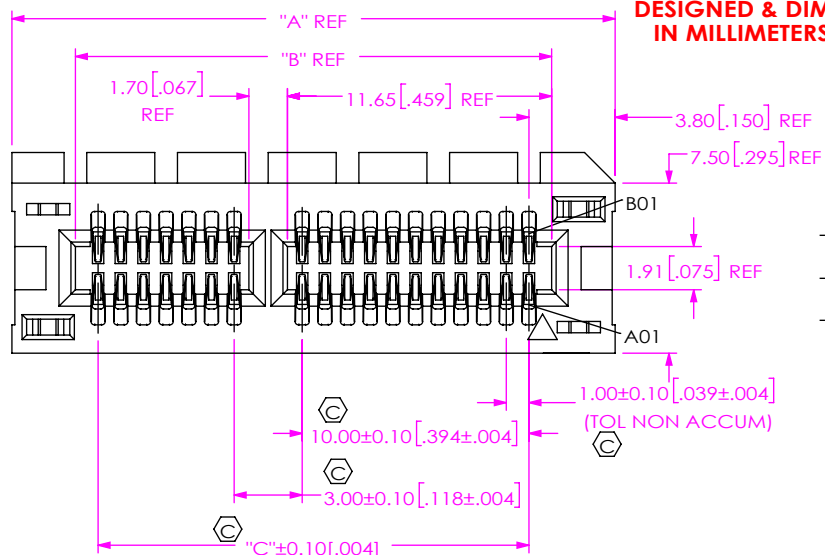
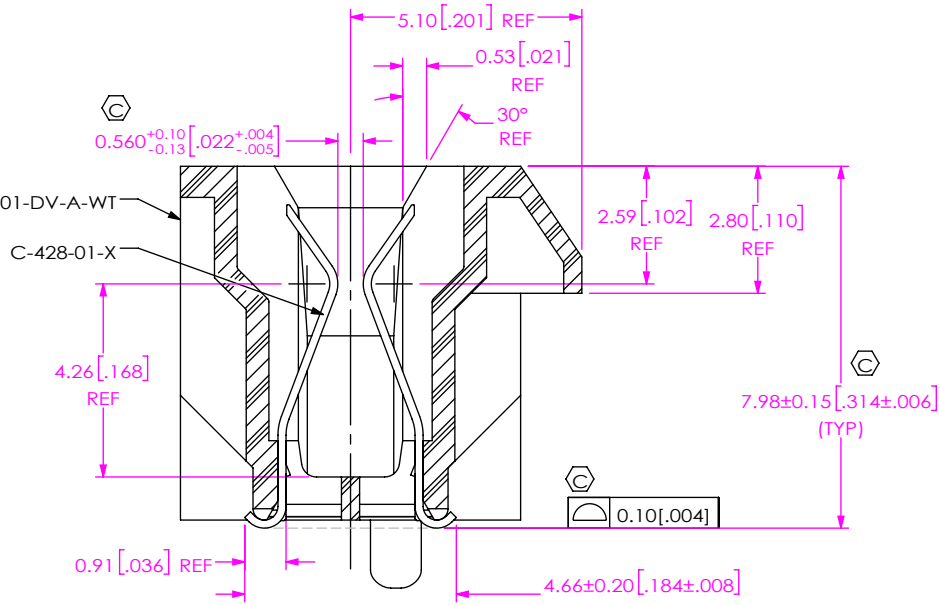


FIG 1

- NOTES:
- ⊕ REPRESENTS A CRITICAL DIMENSION. PCIE-LP-01-01-X-DV-A-XX SHOWN
 - DIMENSIONS MEASURED TIP TO TIP.
 - MINIMUM PUSHOUT FORCE: SIGNAL: 2.2N, WELD TAB: 4.45N.
 - MATING CARD MUST HAVE LEAD-IN. SEE SAMTEC FOOTPRINT FOR SPECIFICATIONS.
 - NOTE DELETED.
 - NOTE DELETED.
 - ORDERS WILL BE PACKAGED ACCORDING TO THE SAMTEC PACKAGING EFFICIENCY STANDARDS (SPES) FOUND ON WWW.SAMTEC.COM.
 - ATTACH LABEL TO EACH REEL.

ALIGNMENT PIN



SECTION "A"-"A"
SCALE 6 : 1

| No OF LANES | "A" | "B" | "C" | "D" | "E" |
|-------------|---------------|---------------|---------------|---------------|---------------|
| -01 | 26.60 [1.047] | 21.00 [0.827] | 19.00 [0.748] | 19.00 [0.748] | 21.70 [0.854] |
| -04 | 40.60 [1.598] | 35.00 [1.378] | 33.00 [1.299] | 33.00 [1.299] | 35.70 [1.406] |
| -08 | 57.60 [2.268] | 52.00 [2.047] | 50.00 [1.969] | 50.00 [1.969] | 52.70 [2.075] |
| -16 | 90.60 [3.567] | 85.00 [3.346] | 83.00 [3.268] | 83.00 [3.268] | 85.70 [3.374] |

UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE IN MILLIMETERS. TOLERANCES ARE:
DECIMALS ANGLES
X.X: ±0.3 [0.1] 2°
X.XX: ±0.13 [0.005]
X.XXX: ±0.051 [0.0020]

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520 PARK EAST BLVD. NEW ALBANY, IN 47150
PHONE: 812-944-6733 FAX: 812-948-5047
e-Mail: info@SAMTEC.com code 55322

MATERIAL: DO NOT SCALE DRAWING SHEET SCALE: 3:1
INSULATOR: LCP, UL 94 V0, COLOR: BLACK
CONTACT: PHOS BRONZE
WELD TAB: BRASS ALLOY

DESCRIPTION:
PCI EXPRESS LOW PROFILE ASSEMBLY
DWG. NO.
PCIE-LP-XX-01-X-DV-A-XX-X-XX

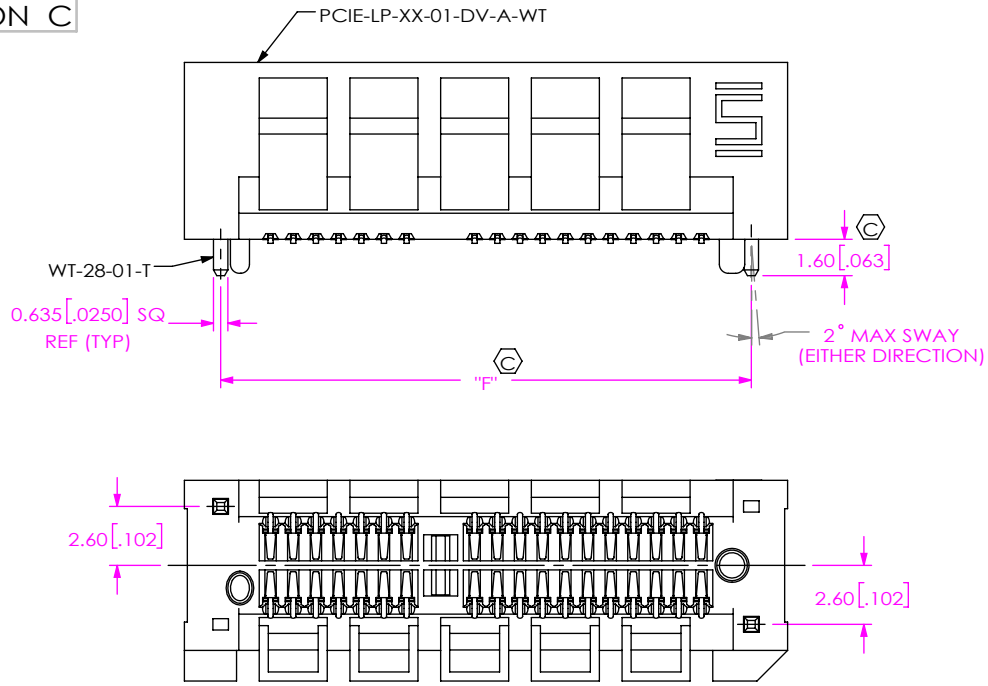
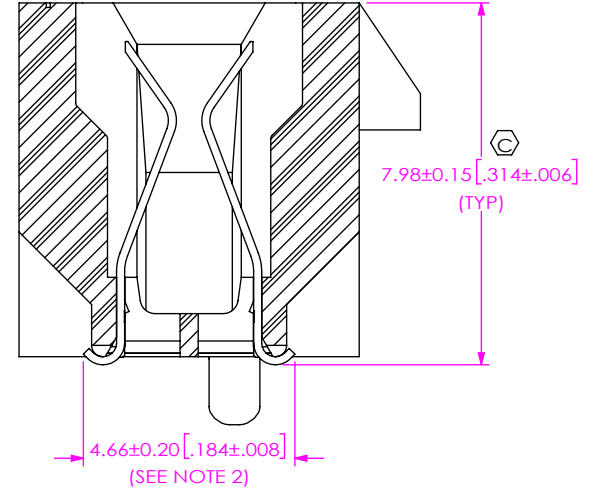


FIG 2
 PCIE-LP-01-01-X-DV-A-WT-XX SHOWN
 (DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)

| No OF LANES | "F" | "G" |
|-------------|---------------|---------------|
| -01 | 23.40 [.921] | 8.80 [.346] |
| -04 | 37.40 [1.472] | 15.80 [.622] |
| -08 | 54.40 [2.142] | 24.30 [.957] |
| -16 | 87.40 [3.441] | 40.80 [1.606] |



IN-PROCESS 1
 (FILL C-428-01-X)

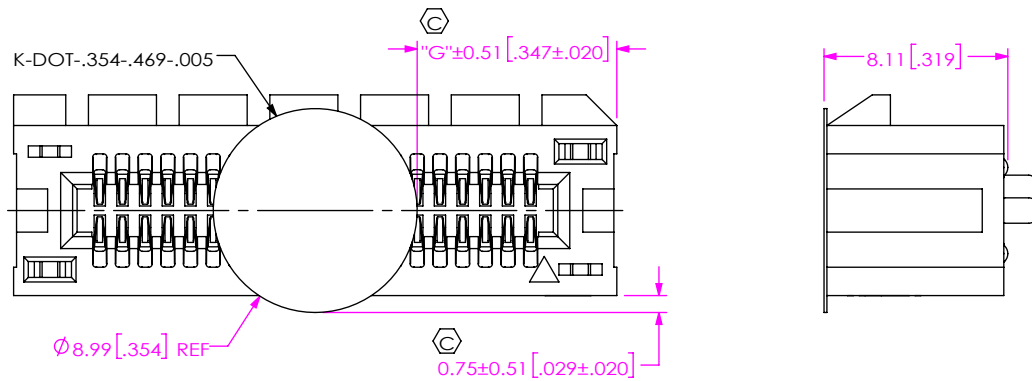


FIG 3
 PCIE-LP-01-01-X-DV-A-K-XX SHOWN
 (DIFFERENT AS SHOWN, OTHERWISE SAME AS FIG 1)

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 PHONE: 812-944-6733 FAX: 812-948-5047
 e-Mail: info@SAMTEC.com code 55322

DO NOT SCALE DRAWING

SHEET SCALE: 3:1

DESCRIPTION:
 PCI EXPRESS LOW PROFILE ASSEMBLY

DWG. NO.
 PCIE-LP-XX-01-X-DV-A-XX-X-XX

BY: JESSIE W 6/30/2016 SHEET 2 OF 2